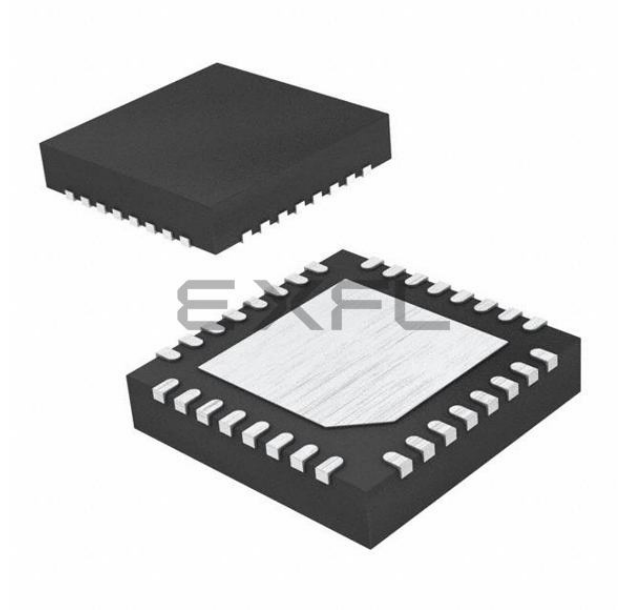
Microchip Technology - PIC24EP256GP202-H/MM Datasheet



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	21
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 150°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN-S (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep256gp202-h-mm

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name(4)	Pin Type	Buffer Type	PPS	Description
U2CTS	I	ST	No	UART2 Clear-To-Send.
U2RTS	O	—	No	UART2 Ready-To-Send.
U2RX	I	ST	Yes	UART2 receive.
U2TX	O	—	Yes	UART2 transmit.
BCLK2	O	ST	No	UART2 IrDA® baud clock output.
SCK1	I/O	ST	No	Synchronous serial clock input/output for SPI1.
SDI1	I	ST	No	SPI1 data in.
SDO1	O	—	No	SPI1 data out.
SS1	I/O	ST	No	SPI1 slave synchronization or frame pulse I/O.
SCK2	I/O	ST	Yes	Synchronous serial clock input/output for SPI2.
SDI2	I	ST	Yes	SPI2 data in.
SDO2	O	—	Yes	SPI2 data out.
SS2	I/O	ST	Yes	SPI2 slave synchronization or frame pulse I/O.
SCL1	I/O	ST	No	Synchronous serial clock input/output for I2C1.
SDA1	I/O	ST	No	Synchronous serial data input/output for I2C1.
ASCL1	I/O	ST	No	Alternate synchronous serial clock input/output for I2C1.
ASDA1	I/O	ST	No	Alternate synchronous serial data input/output for I2C1.
SCL2	I/O	ST	No	Synchronous serial clock input/output for I2C2.
SDA2	I/O	ST	No	Synchronous serial data input/output for I2C2.
ASCL2	I/O	ST	No	Alternate synchronous serial clock input/output for I2C2.
ASDA2	I/O	ST	No	Alternate synchronous serial data input/output for I2C2.
TMS(5)	I	ST	No	JTAG Test mode select pin.
TCK	I	ST	No	JTAG test clock input pin.
TDI	I	ST	No	JTAG test data input pin.
TDO	O	—	No	JTAG test data output pin.
C1RX(2)	I	ST	Yes	ECAN1 bus receive pin.
C1TX(2)	O	—	Yes	ECAN1 bus transmit pin.
FLT1(1), FLT2(1)	I	ST	Yes	PWM Fault Inputs 1 and 2.
FLT3(1), FLT4(1)	I	ST	No	PWM Fault Inputs 3 and 4.
FLT32(1,3)	I	ST	No	PWM Fault Input 32 (Class B Fault).
DTCMP1-DTCMP3(1)	I	ST	Yes	PWM Dead-Time Compensation Inputs 1 through 3.
PWM1L-PWM3L(1)	O	—	No	PWM Low Outputs 1 through 3.
PWM1H-PWM3H(1)	O	—	No	PWM High Outputs 1 through 3.
SYNCI1(1)	I	ST	Yes	PWM Synchronization Input 1.
SYNCO1(1)	O	—	Yes	PWM Synchronization Output 1.
INDX1(1)	I	ST	Yes	Quadrature Encoder Index1 pulse input.
HOME1(1)	I	ST	Yes	Quadrature Encoder Home1 pulse input.
QEA1(1)	I	ST	Yes	Quadrature Encoder Phase A input in QEI1 mode. Auxiliary timer external clock/gate input in Timer mode.
QEB1(1)	I	ST	Yes	Quadrature Encoder Phase B input in QEI1 mode. Auxiliary timer external clock/gate input in Timer mode.
CNTCMP1(1)	O	—	Yes	Quadrature Encoder Compare Output 1.

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
PPS = Peripheral Pin Select; TTL = TTL input buffer

Note 1: This pin is available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: This pin is available on dsPIC33EPXXXGP/MC50X devices only.

3: This is the default Fault on Reset for dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices. See **Section 16.0 "High-Speed PWM Module (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X Devices Only)"** for more information.

4: Not all pins are available in all packages variants. See the **"Pin Diagrams"** section for pin availability.

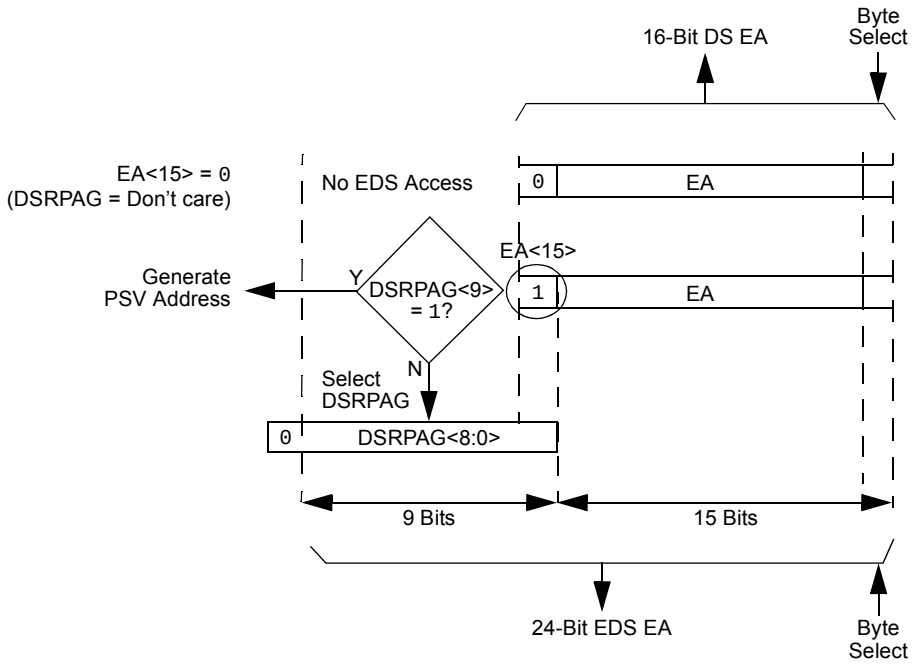
5: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

4.4.1 PAGED MEMORY SCHEME

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X architecture extends the available Data Space through a paging scheme, which allows the available Data Space to be accessed using MOV instructions in a linear fashion for pre-modified and post-modified Effective Addresses (EA). The upper half of the base Data Space address is used in conjunction with the Data Space Page registers, the 10-bit Read Page register (DSRPAG) or the 9-bit Write Page register (DSWPAG), to form an Extended Data Space (EDS) address or Program Space Visibility (PSV) address. The Data Space Page registers are located in the SFR space.

Construction of the EDS address is shown in Example 4-1. When DSRPAG<9> = 0 and the base address bit, EA<15> = 1, the DSRPAG<8:0> bits are concatenated onto EA<14:0> to form the 24-bit EDS read address. Similarly, when base address bit, EA<15> = 1, DSWPAG<8:0> are concatenated onto EA<14:0> to form the 24-bit EDS write address.

EXAMPLE 4-1: EXTENDED DATA SPACE (EDS) READ ADDRESS GENERATION



Note: DS read access when DSRPAG = 0x000 will force an address error trap.

REGISTER 10-1: PMD1: PERIPHERAL MODULE DISABLE CONTROL REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
T5MD	T4MD	T3MD	T2MD	T1MD	QEI1MD(1)	PWMMD(1)	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
I2C1MD	U2MD	U1MD	SPI2MD	SPI1MD	—	C1MD(2)	AD1MD
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **T5MD:** Timer5 Module Disable bit
1 = Timer5 module is disabled
0 = Timer5 module is enabled

bit 14 **T4MD:** Timer4 Module Disable bit
1 = Timer4 module is disabled
0 = Timer4 module is enabled

bit 13 **T3MD:** Timer3 Module Disable bit
1 = Timer3 module is disabled
0 = Timer3 module is enabled

bit 12 **T2MD:** Timer2 Module Disable bit
1 = Timer2 module is disabled
0 = Timer2 module is enabled

bit 11 **T1MD:** Timer1 Module Disable bit
1 = Timer1 module is disabled
0 = Timer1 module is enabled

bit 10 **QEI1MD:** QEI1 Module Disable bit(1)
1 = QEI1 module is disabled
0 = QEI1 module is enabled

bit 9 **PWMMD:** PWM Module Disable bit(1)
1 = PWM module is disabled
0 = PWM module is enabled

bit 8 **Unimplemented:** Read as '0'

bit 7 **I2C1MD:** I2C1 Module Disable bit
1 = I2C1 module is disabled
0 = I2C1 module is enabled

bit 6 **U2MD:** UART2 Module Disable bit
1 = UART2 module is disabled
0 = UART2 module is enabled

bit 5 **U1MD:** UART1 Module Disable bit
1 = UART1 module is disabled
0 = UART1 module is enabled

bit 4 **SPI2MD:** SPI2 Module Disable bit
1 = SPI2 module is disabled
0 = SPI2 module is enabled

Note 1: This bit is available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.
2: This bit is available on dsPIC33EPXXXGP50X and dsPIC33EPXXXMC50X devices only.

REGISTER 11-22: RPOR4: PERIPHERAL PIN SELECT OUTPUT REGISTER 4

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP43R<5:0>					
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP42R<5:0>					
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **RP43R<5:0>:** Peripheral Output Function is Assigned to RP43 Output Pin bits (see Table 11-3 for peripheral function numbers)

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **RP42R<5:0>:** Peripheral Output Function is Assigned to RP42 Output Pin bits (see Table 11-3 for peripheral function numbers)

REGISTER 11-23: RPOR5: PERIPHERAL PIN SELECT OUTPUT REGISTER 5

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP55R<5:0>					
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP54R<5:0>					
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **RP55R<5:0>:** Peripheral Output Function is Assigned to RP55 Output Pin bits (see Table 11-3 for peripheral function numbers)

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **RP54R<5:0>:** Peripheral Output Function is Assigned to RP54 Output Pin bits (see Table 11-3 for peripheral function numbers)

REGISTER 16-14: TRIGx: PWMx PRIMARY TRIGGER COMPARE VALUE REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
TRGCMP<15:8>							
bit 15							bit 8

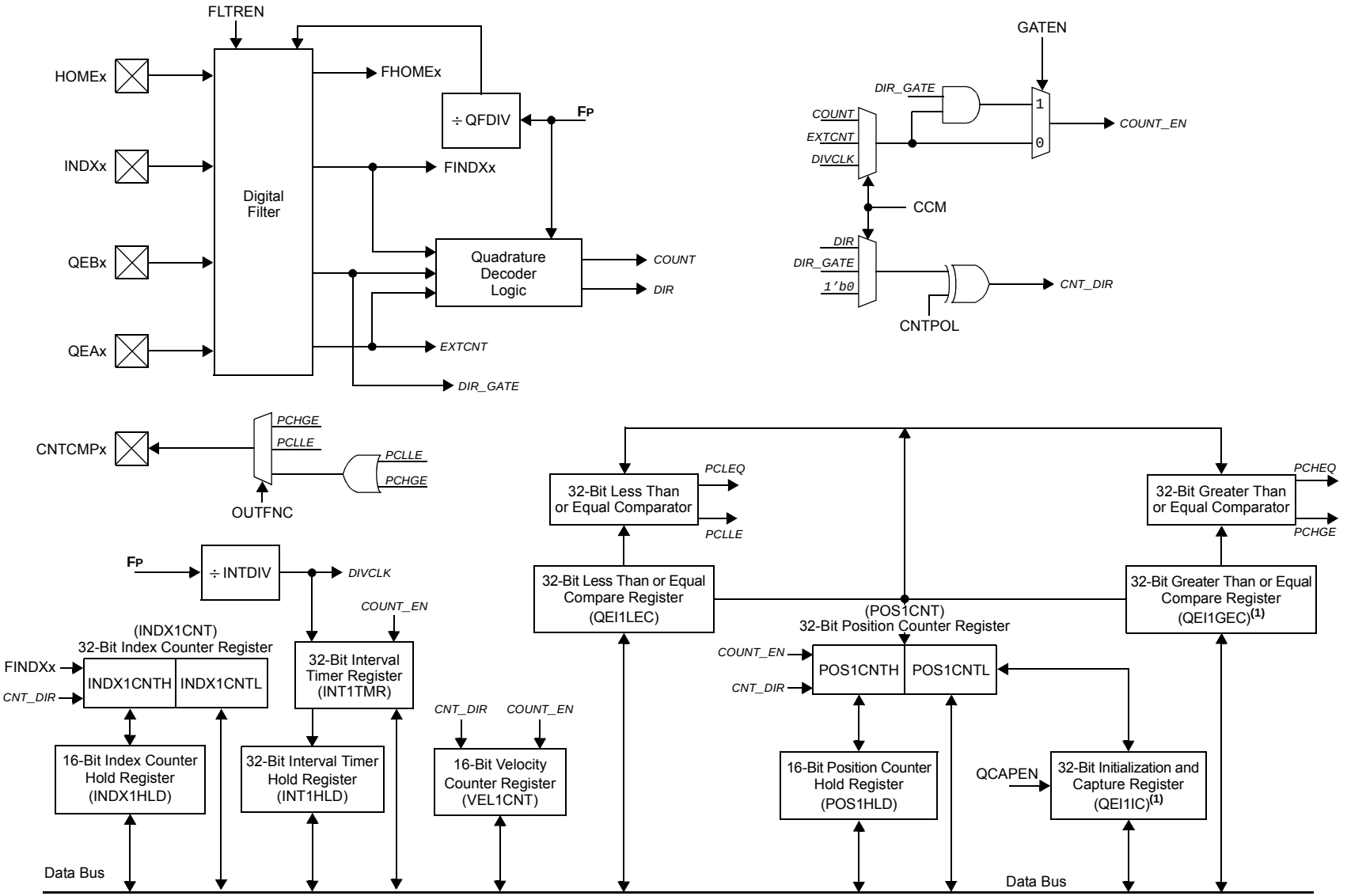
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
TRGCMP<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **TRGCMP<15:0>:** Trigger Control Value bits

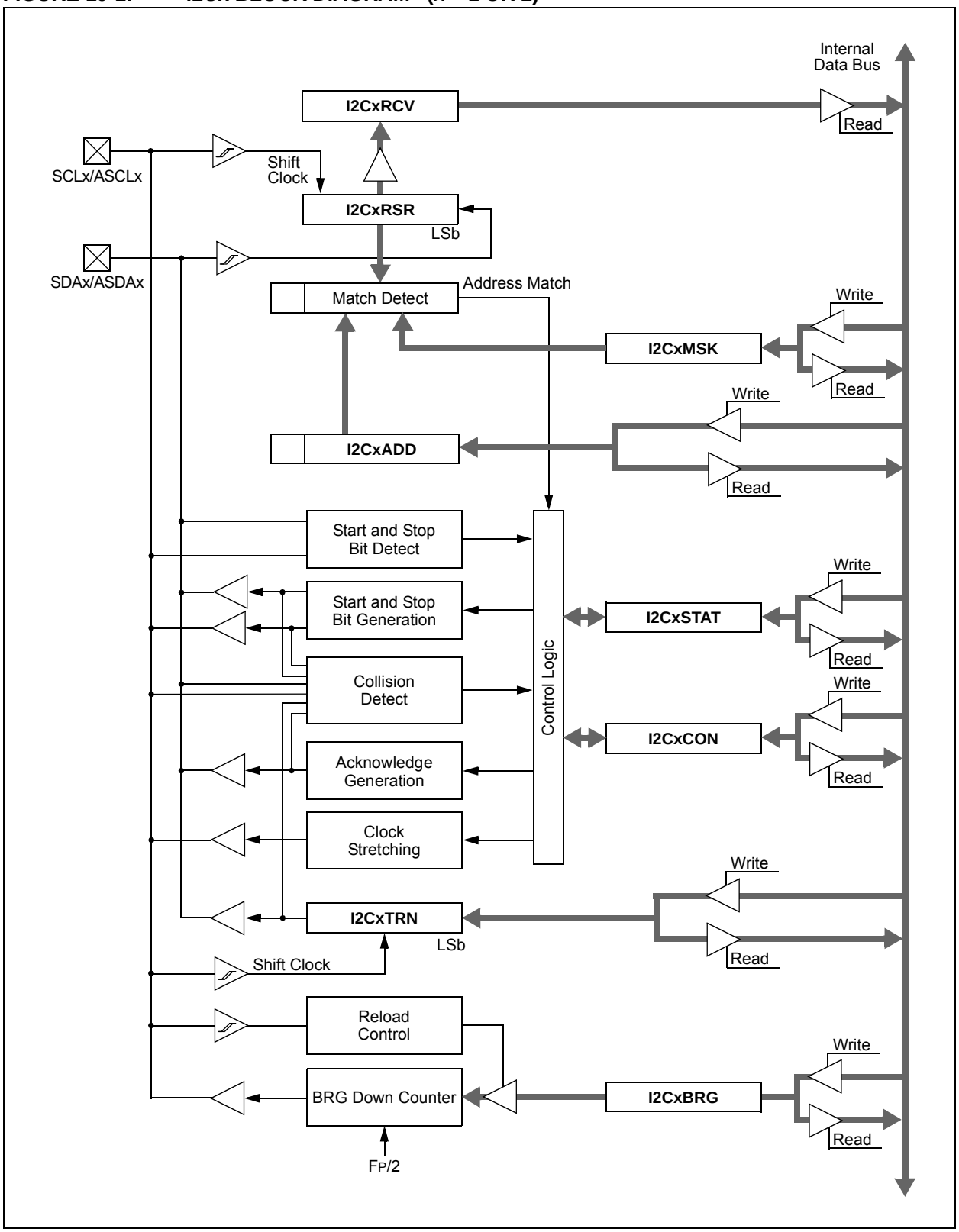
When the primary PWMx functions in local time base, this register contains the compare values that can trigger the ADC module.

FIGURE 17-1: QEI BLOCK DIAGRAM



Note 1: These registers map to the same memory location.

FIGURE 19-1: I2Cx BLOCK DIAGRAM (x = 1 OR 2)



REGISTER 19-2: I2CxSTAT: I2Cx STATUS REGISTER

R-0, HSC	R-0, HSC	U-0	U-0	U-0	R/C-0, HS	R-0, HSC	R-0, HSC
ACKSTAT	TRSTAT	—	—	—	BCL	GCSTAT	ADD10
bit 15							bit 8

R/C-0, HS	R/C-0, HS	R-0, HSC	R/C-0, HSC	R/C-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC
IWCOL	I2COV	D_A	P	S	R_W	RBF	TBF
bit 7							bit 0

Legend:	C = Clearable bit	HS = Hardware Settable bit	HSC = Hardware Settable/Clearable bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ACKSTAT:** Acknowledge Status bit (when operating as I^2C™ master, applicable to master transmit operation)
1 = NACK received from slave
0 = ACK received from slave
Hardware is set or clear at the end of slave Acknowledge.

bit 14 **TRSTAT:** Transmit Status bit (when operating as I^2C master, applicable to master transmit operation)
1 = Master transmit is in progress (8 bits + ACK)
0 = Master transmit is not in progress
Hardware is set at the beginning of master transmission. Hardware is clear at the end of slave Acknowledge.

bit 13-11 **Unimplemented:** Read as '0'

bit 10 **BCL:** Master Bus Collision Detect bit
1 = A bus collision has been detected during a master operation
0 = No bus collision detected
Hardware is set at detection of a bus collision.

bit 9 **GCSTAT:** General Call Status bit
1 = General call address was received
0 = General call address was not received
Hardware is set when address matches general call address. Hardware is clear at Stop detection.

bit 8 **ADD10:** 10-Bit Address Status bit
1 = 10-bit address was matched
0 = 10-bit address was not matched
Hardware is set at the match of the 2nd byte of the matched 10-bit address. Hardware is clear at Stop detection.

bit 7 **IWCOL:** I2Cx Write Collision Detect bit
1 = An attempt to write to the I2CxTRN register failed because the I^2C module is busy
0 = No collision
Hardware is set at the occurrence of a write to I2CxTRN while busy (cleared by software).

bit 6 **I2COV:** I2Cx Receive Overflow Flag bit
1 = A byte was received while the I2CxRCV register was still holding the previous byte
0 = No overflow
Hardware is set at an attempt to transfer I2CxRSR to I2CxRCV (cleared by software).

bit 5 **D_A:** Data/Address bit (when operating as I^2C slave)
1 = Indicates that the last byte received was data
0 = Indicates that the last byte received was a device address
Hardware is clear at a device address match. Hardware is set by reception of a slave byte.

bit 4 **P:** Stop bit
1 = Indicates that a Stop bit has been detected last
0 = Stop bit was not detected last
Hardware is set or clear when a Start, Repeated Start or Stop is detected.

REGISTER 21-19: CxFMSKSEL2: ECANx FILTER 15-8 MASK SELECTION REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F15MSK<1:0>		F14MSK<1:0>		F13MSK<1:0>		F12MSK<1:0>	
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F11MSK<1:0>		F10MSK<1:0>		F9MSK<1:0>		F8MSK<1:0>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **F15MSK<1:0>:** Mask Source for Filter 15 bits
11 = Reserved
10 = Acceptance Mask 2 registers contain mask
01 = Acceptance Mask 1 registers contain mask
00 = Acceptance Mask 0 registers contain mask

bit 13-12 **F14MSK<1:0>:** Mask Source for Filter 14 bits (same values as bits<15:14>)

bit 11-10 **F13MSK<1:0>:** Mask Source for Filter 13 bits (same values as bits<15:14>)

bit 9-8 **F12MSK<1:0>:** Mask Source for Filter 12 bits (same values as bits<15:14>)

bit 7-6 **F11MSK<1:0>:** Mask Source for Filter 11 bits (same values as bits<15:14>)

bit 5-4 **F10MSK<1:0>:** Mask Source for Filter 10 bits (same values as bits<15:14>)

bit 3-2 **F9MSK<1:0>:** Mask Source for Filter 9 bits (same values as bits<15:14>)

bit 1-0 **F8MSK<1:0>:** Mask Source for Filter 8 bits (same values as bits<15:14>)

REGISTER 21-26: CxTRmnCON: ECANx TX/RX BUFFER mn CONTROL REGISTER (m = 0,2,4,6; n = 1,3,5,7)

R/W-0	R-0	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
TXENn	TXABTn	TXLARBn	TXERRn	TXREQn	RTRENn	TXnPRI1	TXnPRI0
bit 15							bit 8

R/W-0	R-0	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
TXENm	TXABTm(1)	TXLARBm(1)	TXERRm(1)	TXREQm	RTRENm	TXmPRI1	TXmPRI0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 See Definition for bits<7:0>, Controls Buffer n

bit 7 **TXENm:** TX/RX Buffer Selection bit
1 = Buffer TRBn is a transmit buffer
0 = Buffer TRBn is a receive buffer

bit 6 **TXABTm:** Message Aborted bit(1)
1 = Message was aborted
0 = Message completed transmission successfully

bit 5 **TXLARBm:** Message Lost Arbitration bit(1)
1 = Message lost arbitration while being sent
0 = Message did not lose arbitration while being sent

bit 4 **TXERRm:** Error Detected During Transmission bit(1)
1 = A bus error occurred while the message was being sent
0 = A bus error did not occur while the message was being sent

bit 3 **TXREQm:** Message Send Request bit
1 = Requests that a message be sent; the bit automatically clears when the message is successfully sent
0 = Clearing the bit to '0' while set requests a message abort

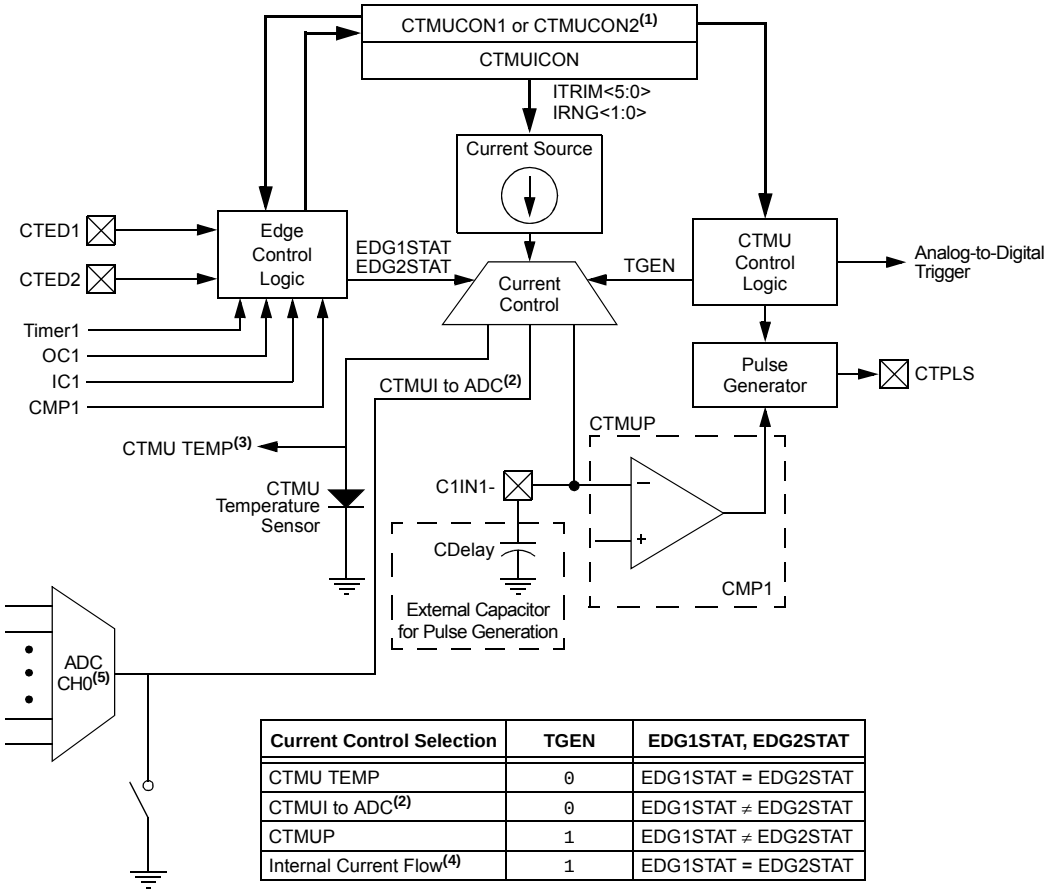
bit 2 **RTRENm:** Auto-Remote Transmit Enable bit
1 = When a remote transmit is received, TXREQ will be set
0 = When a remote transmit is received, TXREQ will be unaffected

bit 1-0 **TXmPRI<1:0>:** Message Transmission Priority bits
11 = Highest message priority
10 = High intermediate message priority
01 = Low intermediate message priority
00 = Lowest message priority

Note 1: This bit is cleared when TXREQ is set.

Note: The buffers, SID, EID, DLC, Data Field, and Receive Status registers are located in DMA RAM.

FIGURE 22-1: CTMU BLOCK DIAGRAM



Current Control Selection	TGEN	EDG1STAT, EDG2STAT
CTMU TEMP	0	EDG1STAT = EDG2STAT
CTMUI to ADC(2)	0	EDG1STAT ≠ EDG2STAT
CTMUP	1	EDG1STAT ≠ EDG2STAT
Internal Current Flow(4)	1	EDG1STAT = EDG2STAT

Note 1: When the CTMU is not actively used, set TGEN = 1, and ensure that EDG1STAT = EDG2STAT. All other settings allow current to flow into the ADC or the C1IN1- pin. If using the ADC for other purposes besides the CTMU, set IDISSEN = 0. If IDISSEN is set to '1', it will short the output of the ADC CH0 MUX to VSS.

2: CTMUI connects to the output of the ADC CH0 MUX. When CTMU current is steered into this node, the current will flow out through the selected ADC channel determined by the CH0 MUX (see the CH0Sx bits in the AD1CHS0 register).

3: CTMU TEMP connects to one of the ADC CH0 inputs; see CH0SA and CH0SB (AD1CHS0<12:8,4:0).

4: If TGEN = 1 and EDG1STAT = EDG2STAT, CTMU current source is still enabled and may be shunted to VSS internally. This should be considered in low-power applications.

5: The switch connected to ADC CH0 is closed when IDISSEN (CTMUCON1<9>) = 1, and opened when IDISSEN = 0.

22.1 CTMU Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

22.1.1 KEY RESOURCES

- **"Charge Time Measurement Unit (CTMU)"** (DS70661) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

REGISTER 24-1: PTGCST: PTG CONTROL/STATUS REGISTER (CONTINUED)

bit 1-0 **PTGITM<1:0>:** PTG Input Trigger Command Operating Mode bits(1)

11 = Single level detect with Step delay not executed on exit of command (regardless of the PTGCTRL command)
10 = Single level detect with Step delay executed on exit of command
01 = Continuous edge detect with Step delay not executed on exit of command (regardless of the PTGCTRL command)
00 = Continuous edge detect with Step delay executed on exit of command

Note 1: These bits apply to the PTGWHI and PTGWLO commands only.

2: This bit is only used with the PTGCTRL step command software trigger option.

3: Use of the PTG Single-Step mode is reserved for debugging tools only.

NOTES:

27.2 User ID Words

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices contain four User ID Words, located at addresses, 0x800FF8 through 0x800FFE. The User ID Words can be used for storing product information such as serial numbers, system manufacturing dates, manufacturing lot numbers and other application-specific information.

The User ID Words register map is shown in Table 27-3.

TABLE 27-3: USER ID WORDS REGISTER MAP

File Name	Address	Bits 23-16	Bits 15-0
FUID0	0x800FF8	—	UID0
FUID1	0x800FFA	—	UID1
FUID2	0x800FFC	—	UID2
FUID3	0x800FFE	—	UID3

Legend: — = unimplemented, read as '1'.

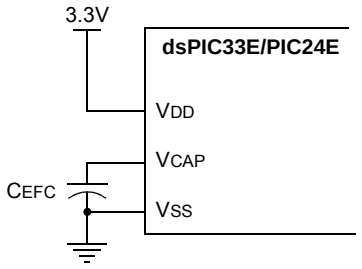
27.3 On-Chip Voltage Regulator

All of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices power their core digital logic at a nominal 1.8V. This can create a conflict for designs that are required to operate at a higher typical voltage, such as 3.3V. To simplify system design, all devices in the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family incorporate an on-chip regulator that allows the device to run its core logic from VDD.

The regulator provides power to the core from the other VDD pins. A low-ESR (less than 1 Ohm) capacitor (such as tantalum or ceramic) must be connected to the VCAP pin (Figure 27-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in Table 30-5 located in **Section 30.0 "Electrical Characteristics"**.

Note:	It is important for the low-ESR capacitor to be placed as close as possible to the VCAP pin.

FIGURE 27-1: CONNECTIONS FOR THE ON-CHIP VOLTAGE REGULATOR(1,2,3)



Note 1: These are typical operating voltages. Refer to Table 30-5 located in **Section 30.1 "DC Characteristics"** for the full operating ranges of VDD and VCAP.

2: It is important for the low-ESR capacitor to be placed as close as possible to the VCAP pin.

3: Typical VCAP pin voltage = 1.8V when VDD ≥ VDDMIN.

27.4 Brown-out Reset (BOR)

The Brown-out Reset (BOR) module is based on an internal voltage reference circuit that monitors the regulated supply voltage, VCAP. The main purpose of the BOR module is to generate a device Reset when a brown-out condition occurs. Brown-out conditions are generally caused by glitches on the AC mains (for example, missing portions of the AC cycle waveform due to bad power transmission lines or voltage sags due to excessive current draw when a large inductive load is turned on).

A BOR generates a Reset pulse, which resets the device. The BOR selects the clock source, based on the device Configuration bit values (FNOSC<2:0> and POSCMD<1:0>).

If an oscillator mode is selected, the BOR activates the Oscillator Start-up Timer (OST). The system clock is held until OST expires. If the PLL is used, the clock is held until the LOCK bit (OSCCON<5>) is '1'.

Concurrently, the PWRT Time-out (TPWRT) is applied before the internal Reset is released. If TPWRT = 0 and a crystal oscillator is being used, then a nominal delay of TFSCM is applied. The total delay in this case is TFSCM. Refer to Parameter SY35 in Table 30-22 of **Section 30.0 "Electrical Characteristics"** for specific TFSCM values.

The BOR status bit (RCON<1>) is set to indicate that a BOR has occurred. The BOR circuit continues to operate while in Sleep or Idle modes and resets the device should VDD fall below the BOR threshold voltage.

29.11 Demonstration/Development Boards, Evaluation Kits and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

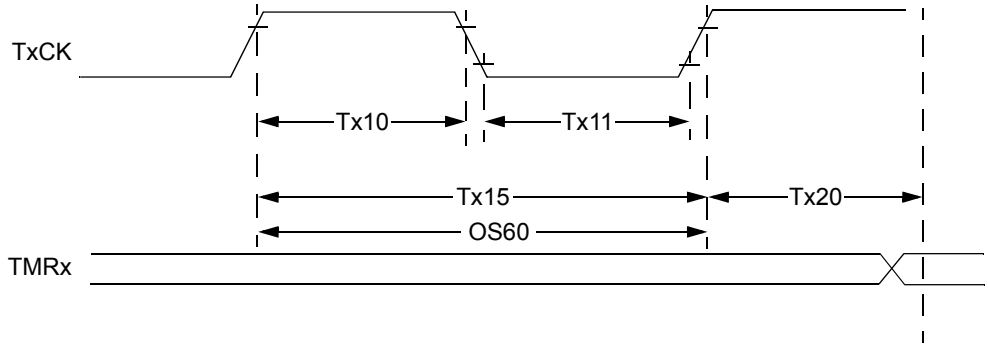
Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

29.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

FIGURE 30-5: TIMER1-TIMER5 EXTERNAL CLOCK TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-23: TIMER1 EXTERNAL CLOCK TIMING REQUIREMENTS(1)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(2)**		**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
TA10	TTXH	T1CK High Time	Synchronous mode	Greater of: 20 or (TCY + 20)/N	—	—	ns	Must also meet Parameter TA15, N = prescaler value (1, 8, 64, 256)
			Asynchronous	35	—	—	ns	
TA11	TTXL	T1CK Low Time	Synchronous mode	Greater of: 20 or (TCY + 20)/N	—	—	ns	Must also meet Parameter TA15, N = prescaler value (1, 8, 64, 256)
			Asynchronous	10	—	—	ns	
TA15	TTXP	T1CK Input Period	Synchronous mode	Greater of: 40 or (2 TCY + 40)/N	—	—	ns	N = prescale value (1, 8, 64, 256)
OS60	Ft1	T1CK Oscillator Input Frequency Range (oscillator enabled by setting bit, TCS (T1CON<1>))		DC	—	50	kHz	
TA20	TCKEXTMRL	Delay from External T1CK Clock Edge to Timer Increment		0.75 TCY + 40	—	1.75 TCY + 40	ns	

Note 1: Timer1 is a Type A.

2: These parameters are characterized, but are not tested in manufacturing.

TABLE 30-37: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK2 Input Frequency	—	—	Lesser of FP or 15	MHz	**(Note 3)**
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS2}$ ↓ to SCK2 ↑ or SCK2 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS2}$ ↑ to SDO2 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{SS2}$ ↑ after SCK2 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**
SP60	TssL2doV	$\overline{SDO2}$ Data Output Valid after $\overline{SS2}$ Edge	—	—	50	ns	

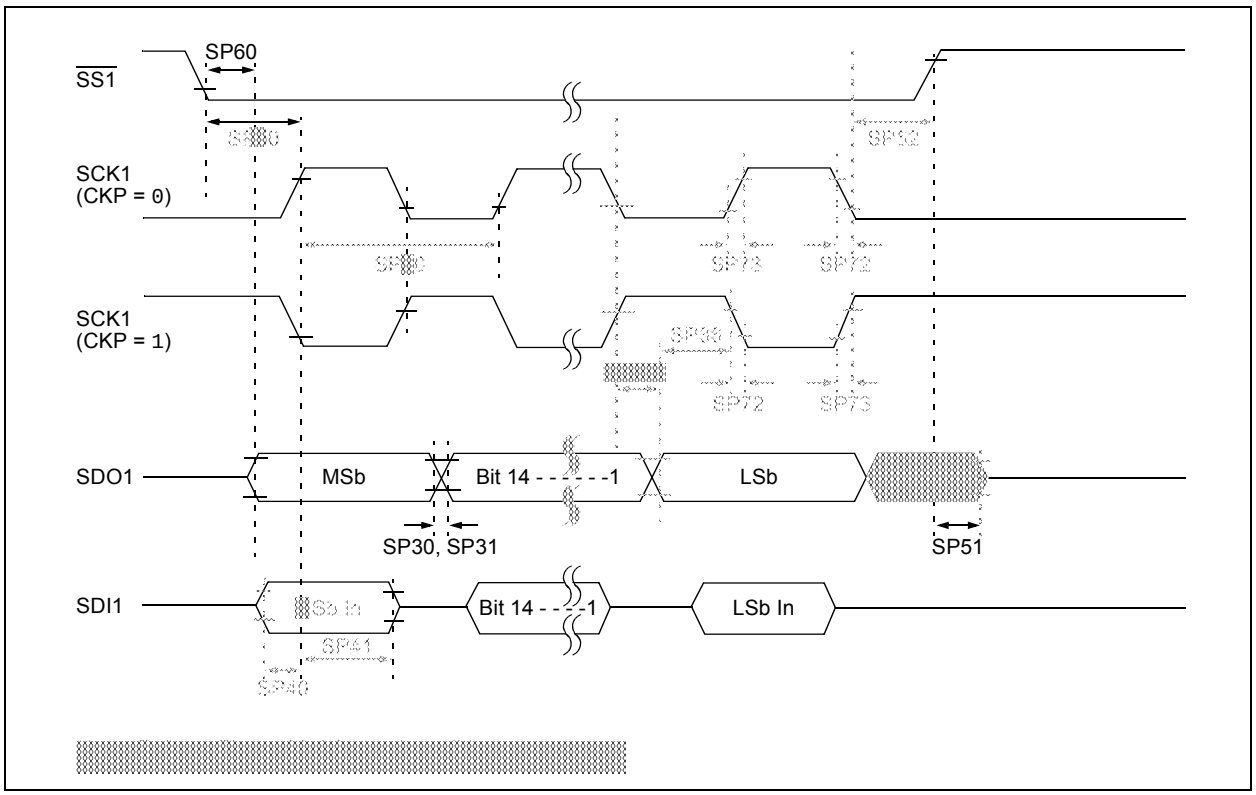
Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 66.7 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.

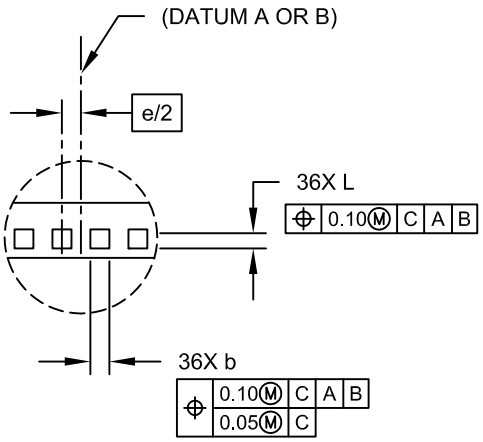
4: Assumes 50 pF load on all SPI2 pins.

FIGURE 30-26: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING CHARACTERISTICS

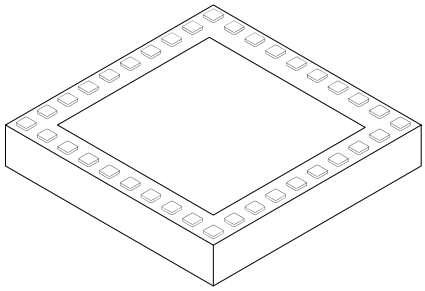


36-Terminal Very Thin Thermal Leadless Array Package (TL) – 5x5x0.9 mm Body with Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



DETAIL A



Units		MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Pins	N		36	
Number of Pins per Side	ND		10	
Number of Pins per Side	NE		8	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.025	-	0.075
Overall Width	E		5.00 BSC	
Exposed Pad Width	E2	3.60	3.75	3.90
Overall Length	D		5.00 BSC	
Exposed Pad Length	D2	3.60	3.75	3.90
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.20	0.25	0.30
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

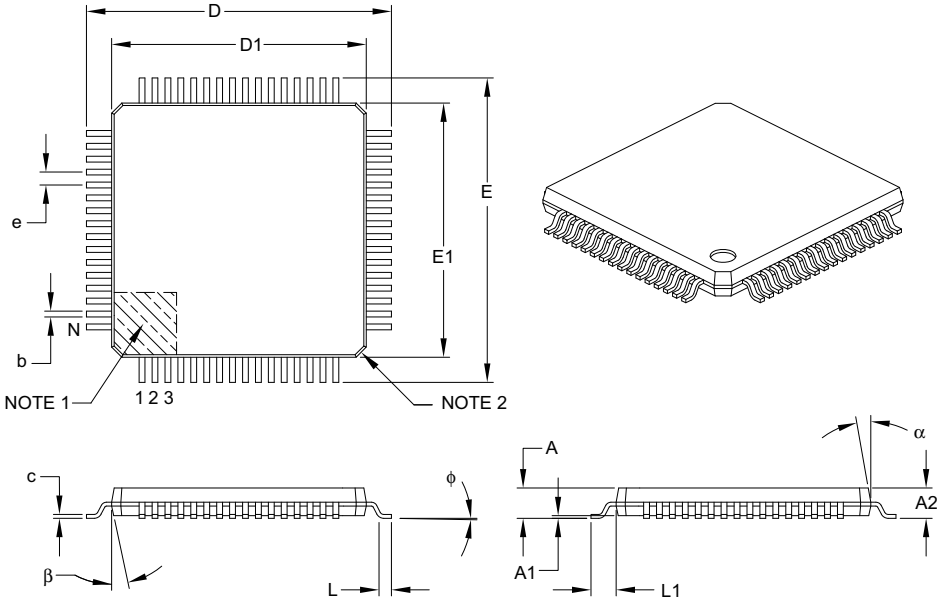
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-187C Sheet 2 of 2

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		64	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	φ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085B